

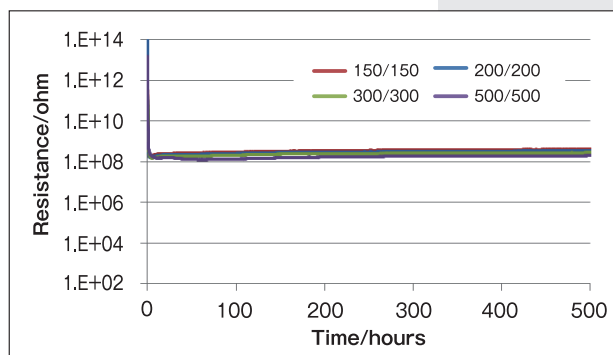
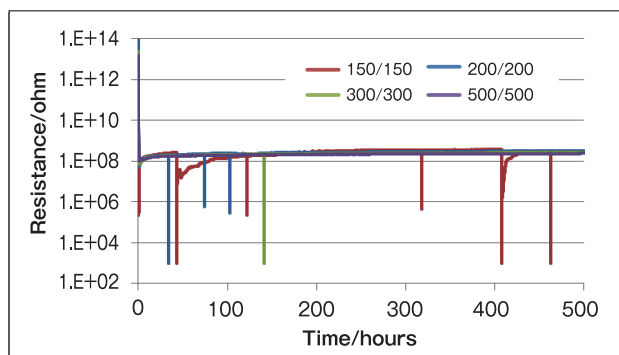
立体成型基板用ソルダーレジスト

3D-MID Solder Resist

13

S-500 MD Series

特長+特性 Features&Properties



SR硬化後無電解Ni/Auめっき

電気特性(85deg.C/85%RH/DC30V 基材:PA)

L/S=150/150, 200/200, 300/300, 500/500 μm

用途 Application

各基材に合わせたMID用ソルダーレジスト

LCP, PPS, PEEK	PBT, PA4T, PA6/6T, PA6T/X, PA10/T, PA1010	PC, PPE, ABS PC/ABS
S-500 MD300 S-500 MD300	S-50 MD200	S-500 MD100

難着性基材との密着性向上

	PA	PPS	LCP	PEEK
改良前				
改良後				